

ABSTRACT OF THE DISCLOSURE

An electronic element includes a substrate with electrode pads provided thereon. Intermediate electrodes include base electrodes on the bottom surface of the intermediate electrodes, and the bottom surface of the intermediate electrodes are disposed on the electrode pads. Bump electrodes are provided on the intermediate electrodes and include a metal having a melting point of about 450°C or more. Further, the base electrodes include a metallic material that can reduce orientation of the intermediate electrodes.